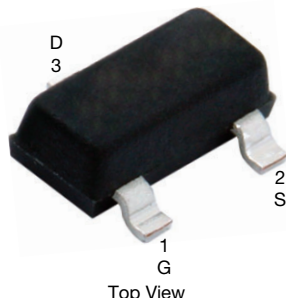


N-Channel 60 V (D-S) MOSFET

SOT-23 (TO-236)



Marking Code: Si2308BDS (L8)

PRODUCT SUMMARY

V_{DS} (V)	60
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10$ V	0.156
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 4.5$ V	0.192
Q_g typ. (nC)	2.3
I_D (A) ^a	2.1
Configuration	Single

ORDERING INFORMATION

Package	TSOP-6 Single
Lead (Pb)-free	SI2308BDS-T1-E3
Lead (Pb)-free and halogen-free	SI2308BDS-T1-GE3
	SI2308BDS-T1-BE3

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage	V_{DS}	60	V
Gate-source voltage	V_{GS}	± 20	V
Continuous drain current ($T_J = 150$ °C)	$T_C = 25$ °C	2.3	A
	$T_C = 70$ °C	1.8	
	$T_A = 25$ °C	1.9 ^{b,c}	
	$T_A = 70$ °C	1.5 ^{b,c}	
Pulsed drain current	I_{DM}	8	A
Continuous source-drain diode current	$T_C = 25$ °C	1.39	
	$T_A = 25$ °C	0.91 ^{b,c}	
Avalanche current	$L = 0.1$ mH	6	
Single pulse avalanche energy	E_{AS}	1.8	W
Maximum power dissipation	$T_C = 25$ °C	1.66	
	$T_C = 70$ °C	1.06	
	$T_A = 25$ °C	1.09 ^{b,c}	
	$T_A = 70$ °C	0.7 ^{b,c}	
Operating junction and storage temperature range	T_J, T_{stg}	-55 to +150	°C

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum Junction-to-Ambient ^{b, d}	R_{thJA}	90	115	°C/W
Maximum Junction-to-Foot (Drain)	R_{thJF}	60	75	

Notes

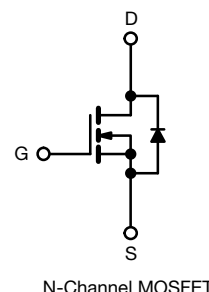
- $T_C = 25$ °C
- Surface mounted on 1" x 1" FR4 board
- $t = 5$ s
- Maximum under steady state conditions is 130 °C/W

FEATURES

- Halogen-free according to IEC 61249-2-21 available
- TrenchFET® power MOSFET
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Battery Switch
- DC/DC Converter


RoHS
COMPLIANT
HALOGEN
FREE




SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V _{DS}	V _{DS} = 0 V, I _D = 250 μA	60	-	-	V
V _{DS} temperature coefficient	ΔV _{DS} /T _J	I _D = 250 μA	-	55	-	mV/°C
V _{GS(th)} temperature coefficient	ΔV _{GS(th)} /T _J		-	-5	-	
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1	-	3	V
Gate-source leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V	-	-	± 100	nA
Zero gate voltage drain current	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V	-	-	1	μA
		V _{DS} = 60 V, V _{GS} = 0 V, T _J = 55 °C	-	-	10	
On-state drain current ^a	I _{D(on)}	V _{DS} ≥ -5 V, V _{GS} = 10 V	8	-	-	A
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 1.9 A	-	0.130	0.156	Ω
		V _{GS} = 4.5 V, I _D = 1.7 A	-	0.160	0.192	
Forward Transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 1.9 A	-	5	-	S
Dynamic ^b						
Input capacitance	C _{iss}	V _{DS} = 30 V, V _{GS} = 0 V, f = 1 MHz	-	190	-	pF
Output capacitance	C _{oss}		-	26	-	
Reverse transfer capacitance	C _{rss}		-	15	-	
Total gate charge	Q _g	V _{DS} = 30 V, V _{GS} = 10 V, I _D = 1.9 A	-	4.5	6.8	nC
		V _{DS} = 30 V, V _{GS} = 4.5 V, I _D = 1.9 A	-	2.3	3.5	
Gate-source charge	Q _{gs}		-	0.8	-	
Gate-drain charge	Q _{gd}		-	1	-	
Gate resistance	R _g	f = 1 MHz	0.6	2.8	5.6	Ω
Turn-on delay time	t _{d(on)}	V _{DD} = 30 V, R _L = 20 Ω I _D ≅ 1.5 A, V _{GEN} = 10 V, R _g = 1 Ω	-	4	6	ns
Rise time	t _r		-	10	15	
Turn-off delay time	t _{d(off)}		-	10	15	
Fall time	t _f		-	7	10.5	
Turn-on delay time	t _{d(on)}	V _{DD} = 30 V, R _L = 20 Ω I _D = 1.5 A, V _{GEN} = 4.5 V, R _g = 1 Ω	-	15	23	
Rise time	t _r		-	16	24	
Turn-off delay time	t _{d(off)}		-	11	17	
Fall time	t _f		-	11	17	
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	1.39	A
Pulse diode forward current ^a	I _{SM}		-	-	8	
Body diode voltage	V _{SD}	I _S = 1.5 A	-	0.8	1.2	V
Body diode reverse recovery time	t _{rr}	I _F = 1.5 A, dI/dt = 100 A/μs, T _J = 25 °C	-	15	23	ns
Body diode reverse recovery charge	Q _{rr}		-	10	15	nC
Reverse recovery fall time	t _a		-	12	-	ns
Reverse recovery rise time	t _b		-	3	-	

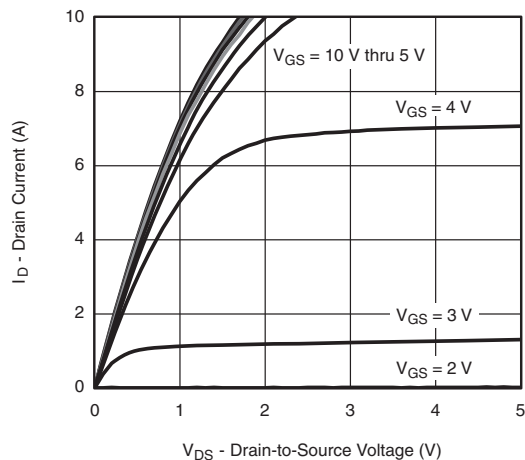
Notes

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing

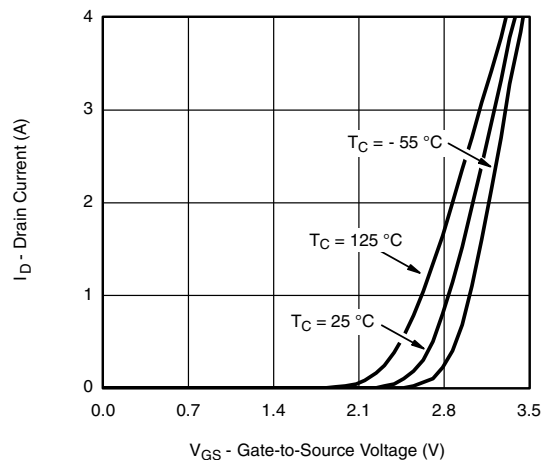
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



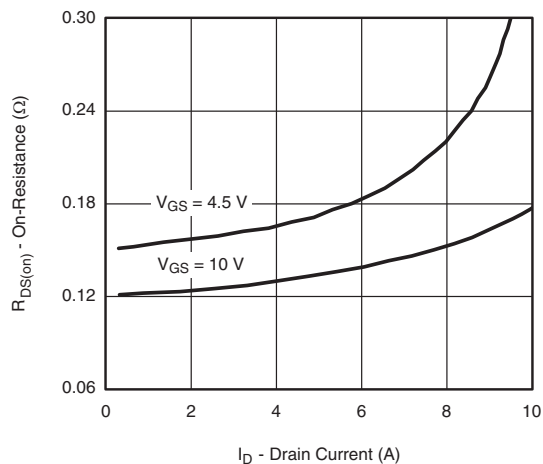
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



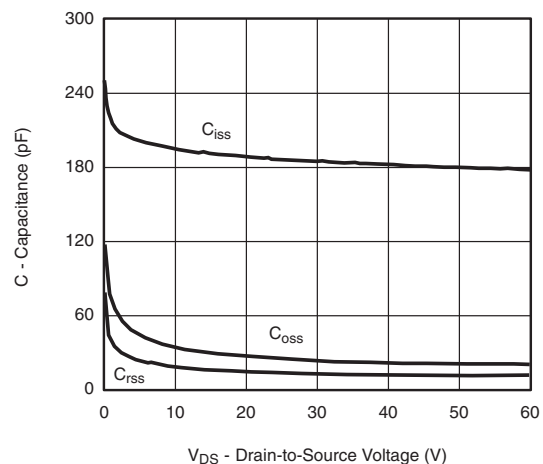
Output Characteristics



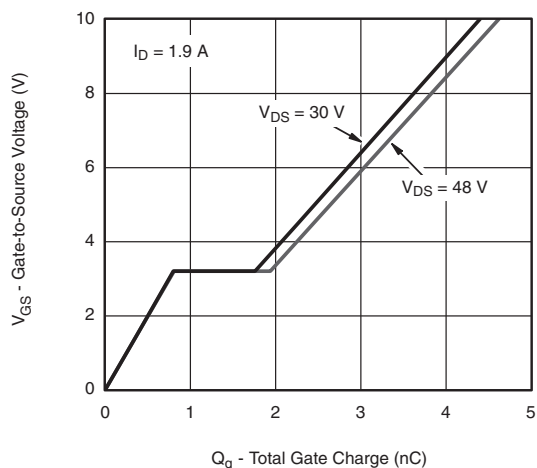
Transfer Characteristics



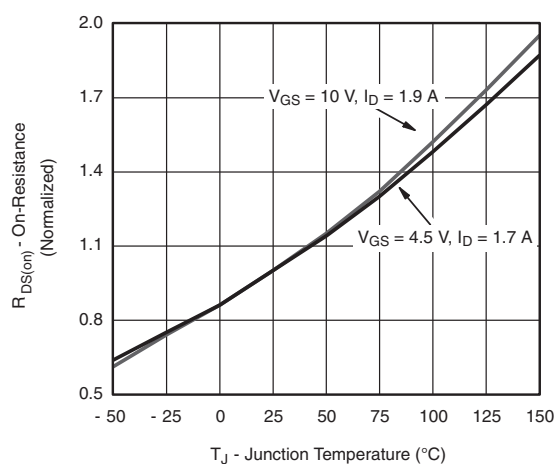
On-Resistance vs. Drain Current



Capacitance



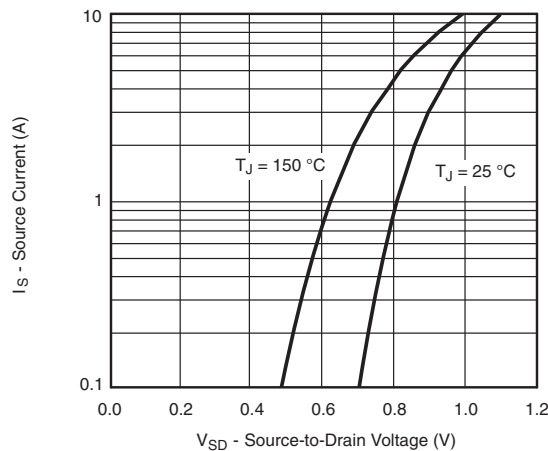
Gate Charge



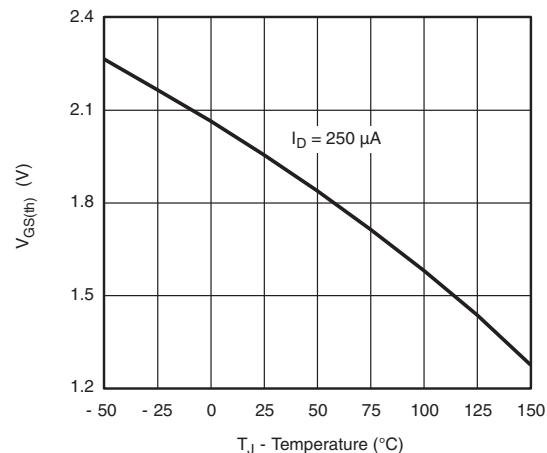
On-Resistance vs. Junction Temperature



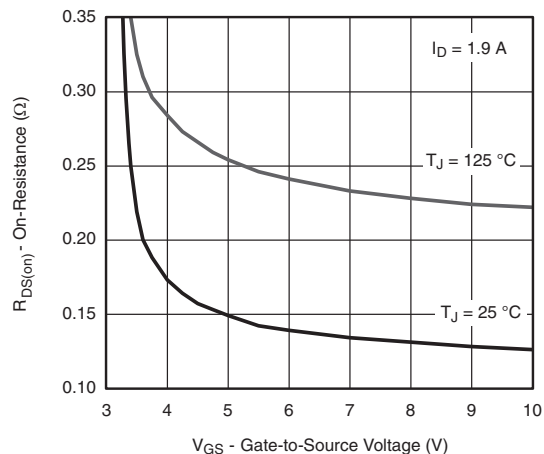
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



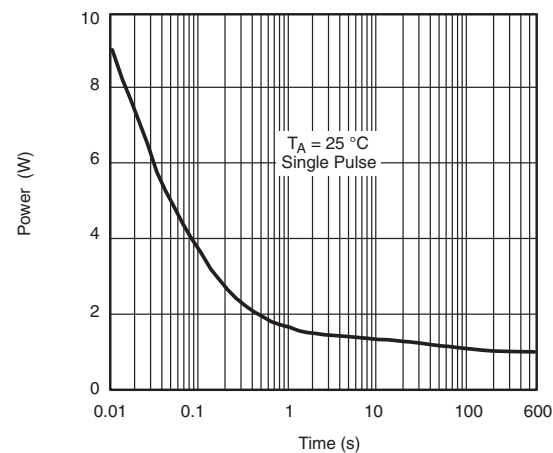
Source-Drain Diode Forward Voltage



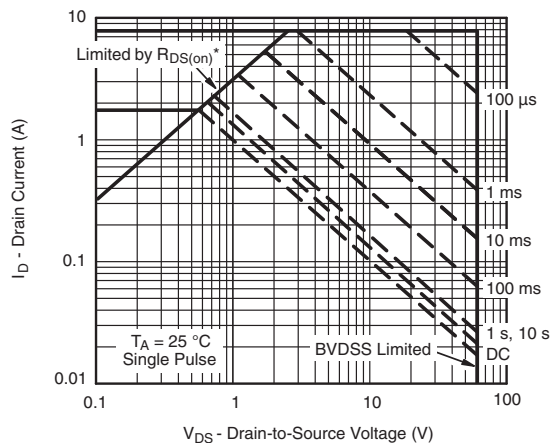
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage

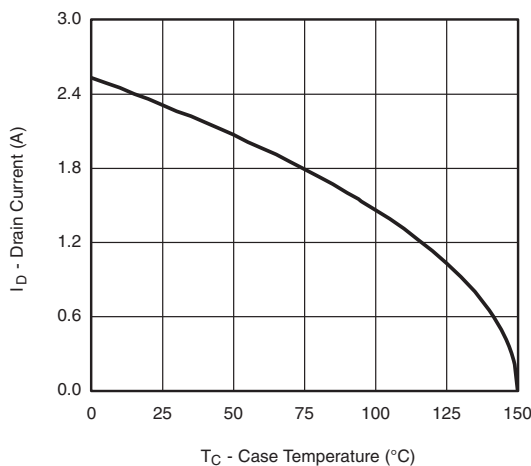
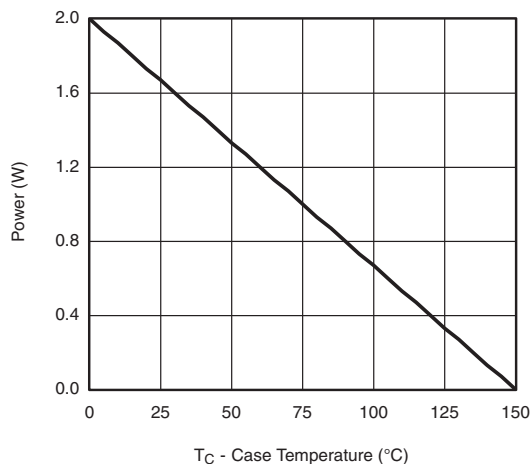
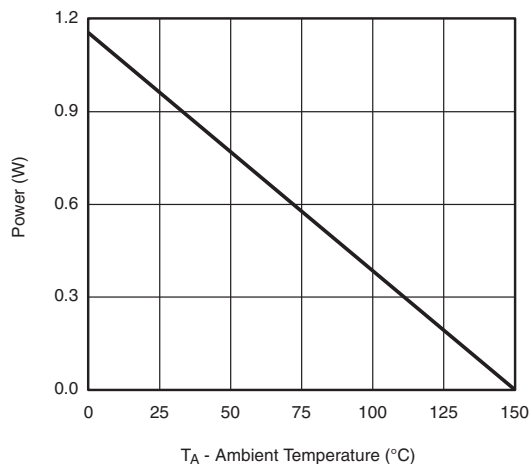


Single Pulse Power, Junction-to-Ambient



* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

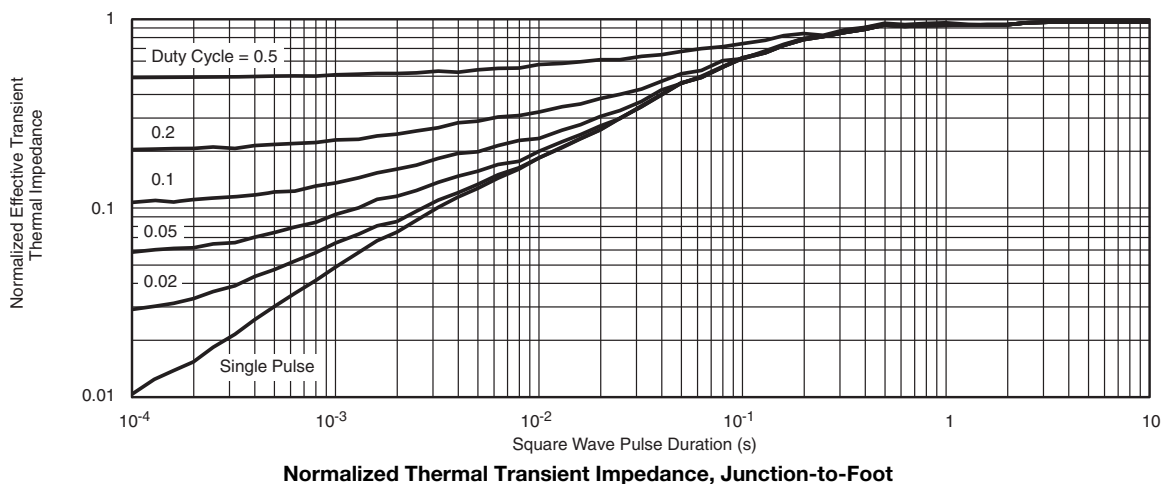
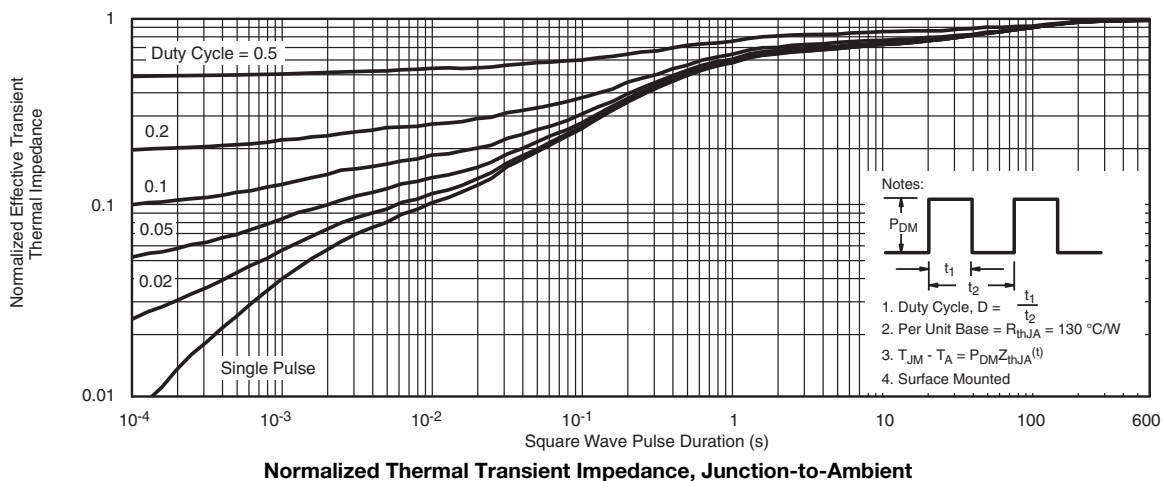
Safe Operating Area

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Current Derating ^a

Power Junction-to-Case

Power Junction-to-Ambient
Note

- a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



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SOT-23 (TO-236): 3-LEAD



Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	0.89	1.12	0.035	0.044
A ₁	0.01	0.10	0.0004	0.004
A ₂	0.88	1.02	0.0346	0.040
b	0.35	0.50	0.014	0.020
c	0.085	0.18	0.003	0.007
D	2.80	3.04	0.110	0.120
E	2.10	2.64	0.083	0.104
E ₁	1.20	1.40	0.047	0.055
e	0.95 BSC		0.0374 Ref	
e ₁	1.90 BSC		0.0748 Ref	
L	0.40	0.60	0.016	0.024
L ₁	0.64 Ref		0.025 Ref	
S	0.50 Ref		0.020 Ref	
q	3°	8°	3°	8°
ECN: S-03946-Rev. K, 09-Jul-01				
DWG: 5479				

RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads
Dimensions in Inches/(mm)

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